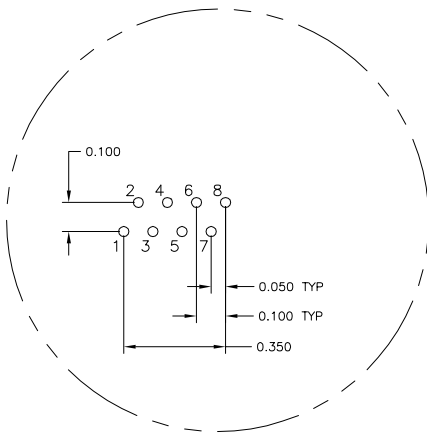
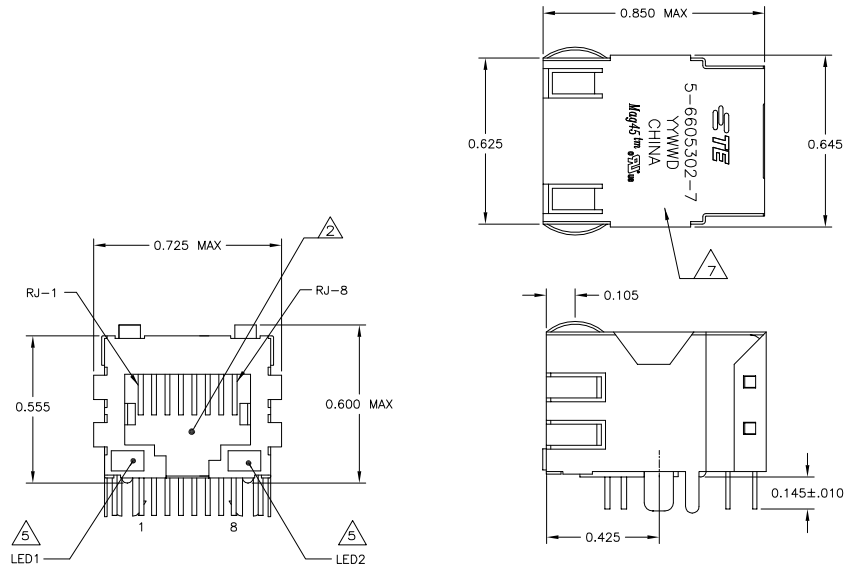


| LOC | DATE | REVISIONS | DATE | BY | APP |
|-----|------|---------------------------|-----------|----|-----|
| AA | 22 | | | | |
| B1 | | REVISED PER ECO-11-005140 | 25MAR11 | RK | HMR |
| C | | ECO-11-015766 | 30MAY2011 | EL | LR |

MECHANICAL:



Pin Designations

NOTES:

MATERIALS:
 HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 11dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

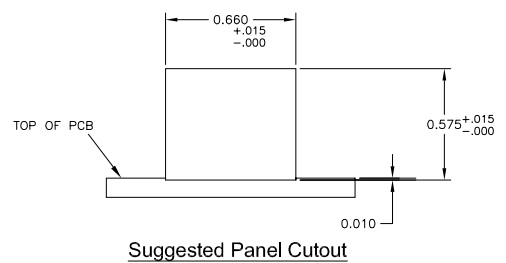
OPERATING TEMPERATURE: FROM 0°C - +70°C

LEDS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA.
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20mA
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20mA.

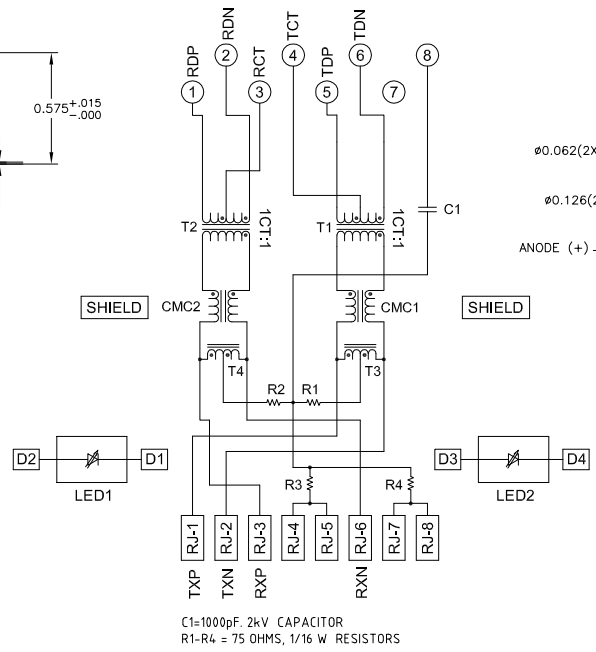
INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORT AUTO-MDI/MDIX.

TE CONNECTIVITY LOGO, TE CONNECTIVITY PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

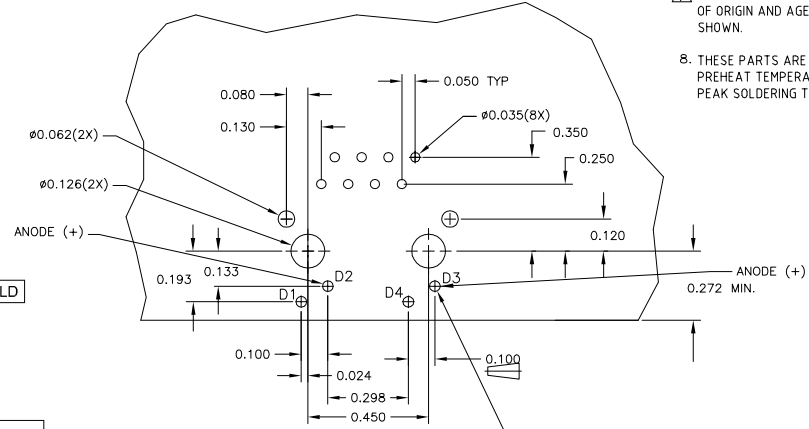
THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.



315 SERIES MAGNETIC CIRCUIT



C1=1000pF, 2kV CAPACITOR
 R1-R4 = 75 OHMS, 1/16 W RESISTORS



Suggested PCB Layout (Component Side)

| YES | GREEN | YELLOW | 5-6605302-8 |
|--------------------------|-------|-------------|-------------|
| YES | GREEN | GREEN | 5-6605302-7 |
| 2KV DECOUPLING CAPACITOR | | LED1 | LED2 |
| | | PART NUMBER | |

| | | | |
|--|--------------|--|--|
| THIS DRAWING IS A CONTROLLED DOCUMENT. | | REV. ATTADIA - 0000000 | |
| DIMENSIONS: INCHES | | REV. FAROLE - 0000000 | |
| 0 PAC ± .010 | 1 PAC ± .010 | NAME | |
| 2 PAC ± .010 | 3 PAC ± .008 | 1X1 MAG45(TM), 4N2 SCHEMATIC, (10/100 ETHERNET), 315 SERIES CIRCUIT, DECOUPLING CAPACITOR, WITH LEDS | |
| 4 PAC ± .008 | 5 PAC ± .008 | PRODUCT SPEC 108-2100 | |
| 6 PAC ± .008 | 7 PAC ± .008 | APPLICATION SPEC | |
| 8 PAC ± .008 | 9 PAC ± .008 | SIZE DATE CODE DRAWING NO | |
| MATERIAL | | A1 00779 C=6605302 | |
| FINISH | | SCALE SHEET 1 OF 1 REV C | |
| CUSTOMER DRAWING | | RESTRICTED TO | |